Special Issue

Advances in Design, Packaging and Verification of Low-Power Integrated Circuits

Message from the Guest Editors

Rapid developments in AI, embodied intelligence, edge computing, and cyber–physical systems give rise to different challenges involving complex design trade-offs. Emerging applications demand energy-efficient solutions and higher levels of performance, reliability, and intelligence based on smart technology, while also demanding applications smaller in size and that use less power. The need to establish an appropriate balance between these contradictory requirements is driving the evolution of ICs and systems. Therefore, the main objective of this SI is to host emerging research and recent developments, reviews, and results in the field of the design, packaging, and verification of low-power ICs. Relevant topics include, but are not limited to, the following:

- System/Network-on-a-chip design;
- Domain-specific accelerator design;
- Software hardware co-design;
- Low-power memory design;
- Design and verification of multi-die integration;
- Chiplet interconnect design;
- Advanced packaging and system integration;
- Data converters—ADCs and DACs;
- Application of artificial intelligence in ICs;
- Reliability design and evaluation of digital ICs;

Guest Editors

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Deadline for manuscript submissions

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About the Journal

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guestedited by leading experts in selected topics of interest.

Editor-in-Chief

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manuscripts are peer-reviewed and a first decision is provided to authors approximately 16.8 days after submission; acceptance to publication is undertaken in 2.4 days (median values for papers published in this journal in the first half of 2025).